



# STGW20NB60HD

## N-CHANNEL 20A - 600V TO-247 PowerMESH™ IGBT

TYPE	V <sub>CES</sub>	V <sub>CE(sat)</sub>	I <sub>C</sub>
STGW20NB60HD	600 V	< 2.8 V	20 A

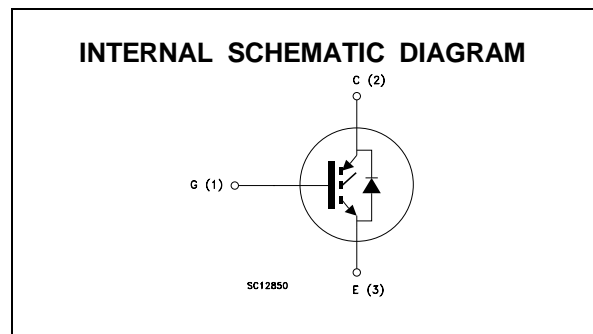
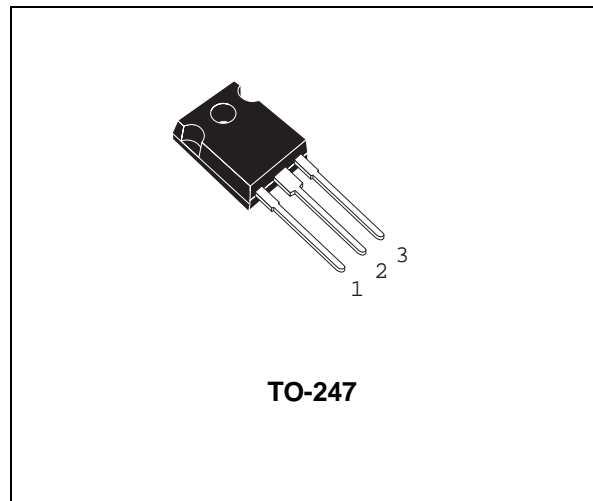
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V<sub>CESAT</sub>)
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- VERY HIGH FREQUENCY OPERATION
- OFF LOSSES INCLUDE TAIL CURRENT
- CO-PACKAGED WITH TURBOSWITCH™ ANTIPARALLEL DIODE

### DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "H" identifies a family optimized to achieve very low switching times for high frequency applications (<120kHz).

### APPLICATIONS

- HIGH FREQUENCY MOTOR CONTROLS
- WELDING EQUIPMENTS
- SMPS AND PFC IN BOTH HARD SWITCH AND RESONANT TOPOLOGIES



### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>GS</sub> = 0)	600	V
V <sub>GE</sub>	Gate-Emitter Voltage	± 20	V
I <sub>C</sub>	Collector Current (continuous) at T <sub>c</sub> = 25 °C	40	A
I <sub>C</sub>	Collector Current (continuous) at T <sub>c</sub> = 100 °C	20	A
I <sub>CM</sub> (•)	Collector Current (pulsed)	160	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	150	W
	Derating Factor	1.2	W/°C
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
T <sub>j</sub>	Max. Operating Junction Temperature	150	°C

(•) Pulse width limited by safe operating area

## STGW20NB60HD

### THERMAL DATA

R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	0.83	°C/W
R <sub>thj-amb</sub>	Thermal Resistance Junction-ambient	Max	30	°C/W
R <sub>thc-h</sub>	Thermal Resistance Case- heatsink	Typ	0.1	°C/W

### ELECTRICAL CHARACTERISTICS (T<sub>j</sub> = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>BR(CES)</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = 250 μA V <sub>GE</sub> = 0	600			V
I <sub>CES</sub>	Collector cut-off (V <sub>GE</sub> = 0)	V <sub>CE</sub> = Max Rating T <sub>j</sub> = 25 °C V <sub>CE</sub> = Max Rating T <sub>j</sub> = 125 °C			250 2000	μA μA
I <sub>GES</sub>	Gate-Emitter Leakage Current (V <sub>CE</sub> = 0)	V <sub>GE</sub> = ± 20 V V <sub>CE</sub> = 0			± 100	nA

ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GE(th)</sub>	Gate Threshold Voltage	V <sub>CE</sub> = V <sub>GE</sub> I <sub>C</sub> = 250 μA	3		5	V
V <sub>CE(SAT)</sub>	Collector-Emitter Saturation Voltage	V <sub>GE</sub> = 15 V I <sub>C</sub> = 20 A V <sub>GE</sub> = 15 V I <sub>C</sub> = 20 A T <sub>j</sub> = 125 °C		2.3 1.9	2.8	V V

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub>	Forward Transconductance	V <sub>CE</sub> = 25 V I <sub>C</sub> = 20 A	7.0	10		S
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>CE</sub> = 25 V f = 1 MHz V <sub>GE</sub> = 0	1200 140 28	1700 200 40	2200 260 52	pF pF pF
Q <sub>G</sub> Q <sub>GE</sub> Q <sub>GC</sub>	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	V <sub>CE</sub> = 480 V I <sub>C</sub> = 20 A V <sub>GE</sub> = 15 V		110 13 51	145	nC nC nC
I <sub>CL</sub>	Latching Current	V <sub>clamp</sub> = 480 V R <sub>G</sub> = 10 Ω T <sub>j</sub> = 150 °C	80			A

### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Delay Time Rise Time	V <sub>CC</sub> = 480 V I <sub>C</sub> = 20 A V <sub>GE</sub> = 15 V R <sub>G</sub> = 10 Ω		20 70		ns ns
(di/dt) <sub>on</sub>	Turn-on Current Slope	V <sub>CC</sub> = 480 V I <sub>C</sub> = 20 A R <sub>G</sub> = 10 Ω V <sub>GE</sub> = 15 V		350		A/μs
E <sub>on(▷)</sub>	Turn-on Switching Losses	T <sub>j</sub> = 125 °C		550		μJ

**ELECTRICAL CHARACTERISTICS** (continued)

**SWITCHING OFF**

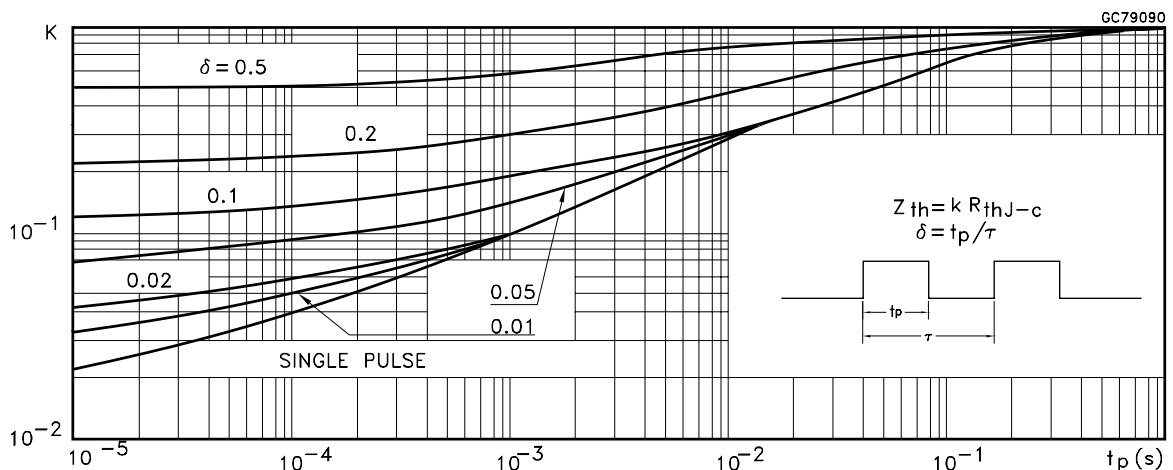
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_c$	Cross-Over Time	$V_{CC} = 480\text{ V}$		115		ns
$t_r(V_{off})$	Off Voltage Rise Time	$I_C = 20\text{ A}$		32		ns
$t_{d(off)}$	Delay Time	$R_{GE} = 10\ \Omega$		170		ns
$t_f$	Fall Time	$V_{GE} = 15\text{ V}$		75		ns
$E_{off(**)}$	Turn-off Switching Loss			0.4		mJ
$E_{ts(\circ)}$	Total Switching Loss			0.9		mJ
$t_c$	Cross-Over Time	$V_{CC} = 480\text{ V}$		190		ns
$t_r(V_{off})$	Off Voltage Rise Time	$R_{GE} = 10\ \Omega$		55		ns
$t_{d(off)}$	Delay Time	$T_j = 125\text{ }^\circ\text{C}$		210		ns
$t_f$	Fall Time			140		ns
$E_{off(**)}$	Turn-off Switching Loss			0.7		mJ
$E_{ts(\circ)}$	Total Switching Loss			1.25		mJ

**COLLECTOR-EMITTER DIODE**

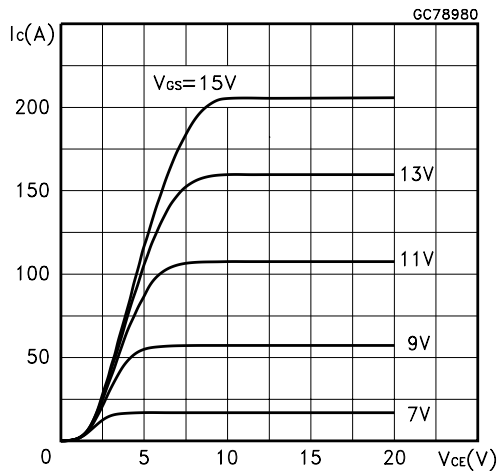
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_f$	Forward Current				20	A
$I_{fm}$	Forward Current pulsed				160	A
$V_f$	Forward On-Voltage	$I_f = 20\text{ A}$		1.50	2.0	V
		$I_f = 20\text{ A}$		1.25		V
		$T_j = 125\text{ }^\circ\text{C}$				
$t_{rr}$	Reverse Recovery Time	$I_f = 20\text{ A}$		100		nS
$Q_{rr}$	Reverse Recovery Charge	$dI/dt = 100\text{ A}/\mu\text{S}$		300		nC
$I_{rrm}$	Reverse Recovery Current	$T_j = 125\text{ }^\circ\text{C}$		5.9		A

- (●) Pulse width limited by max. junction temperature
- (◊) Include recovery losses on the STTA2006 freewheeling diode
- (\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %
- (\*\*) Losses Include Also The Tail (Jedec Standardization)

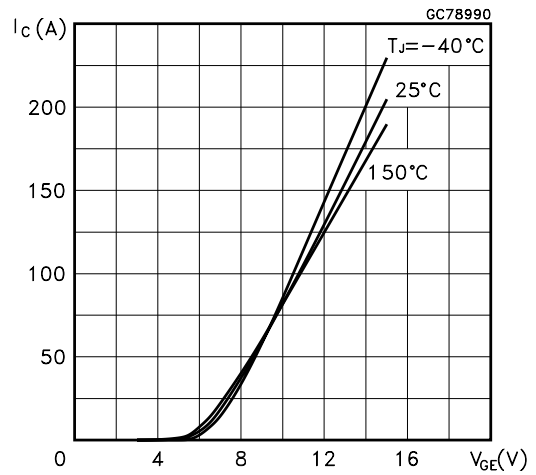
**Thermal Impedance**



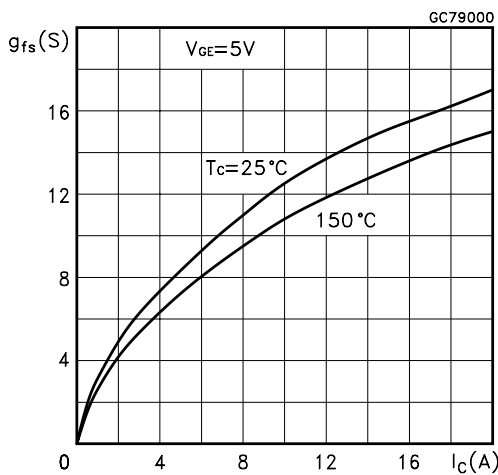
Output Characteristics



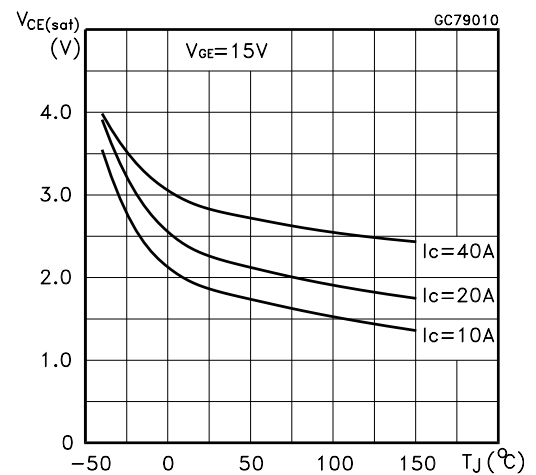
Transfer Characteristics



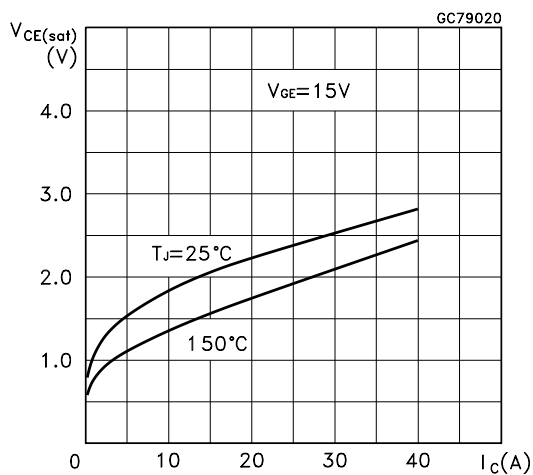
Transconductance



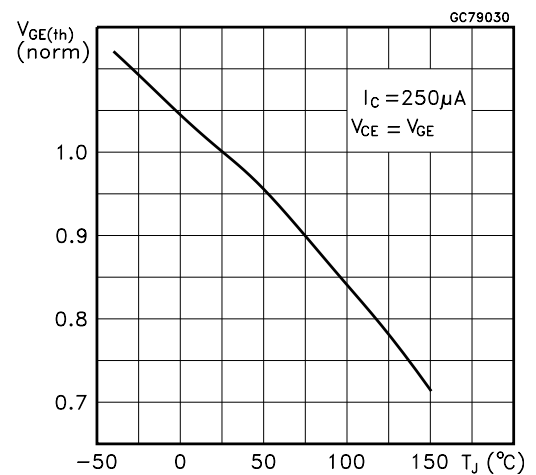
Collector-Emitter On Voltage vs Temperature



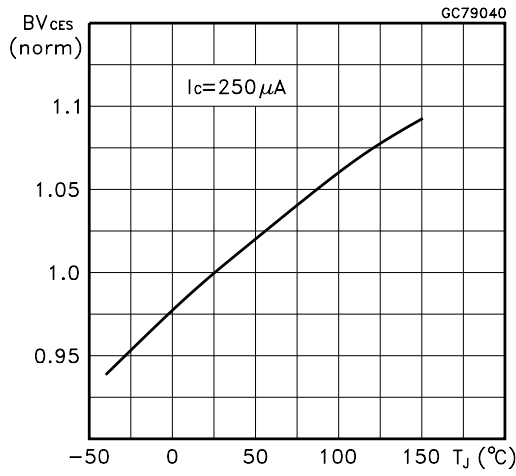
Collector-Emitter On Voltage vs Collector Current



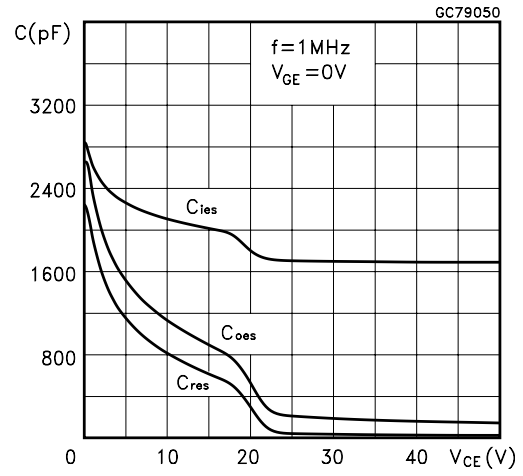
Gate Threshold vs Temperature



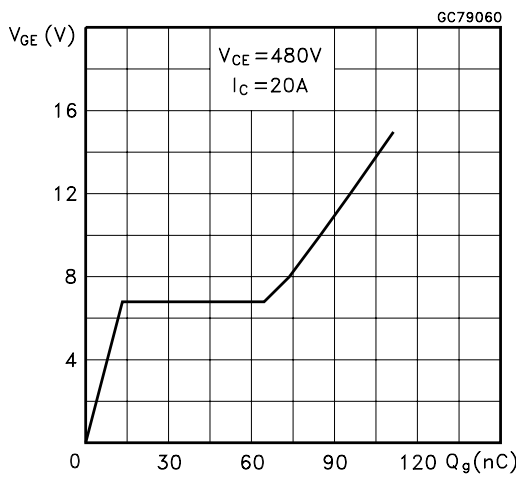
Normalized Breakdown Voltage vs Temperature



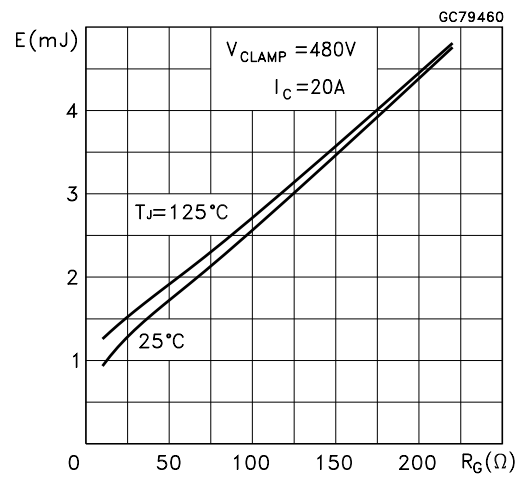
Capacitance Variations



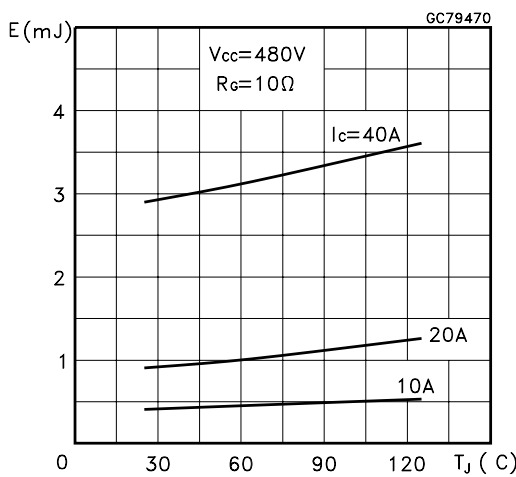
Gate Charge vs Gate-Emitter Voltage



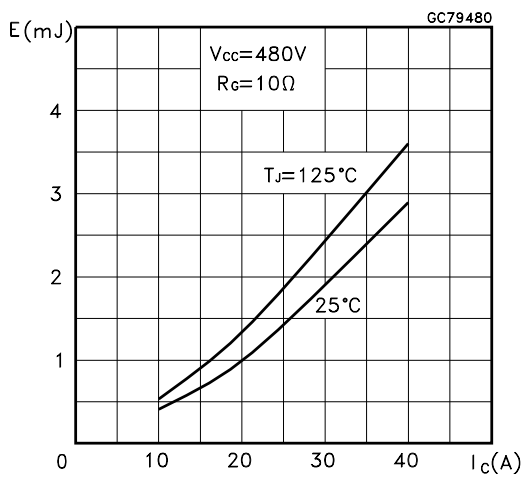
Total Switching Losses vs Gate Resistance



Total Switching Losses vs Temperature



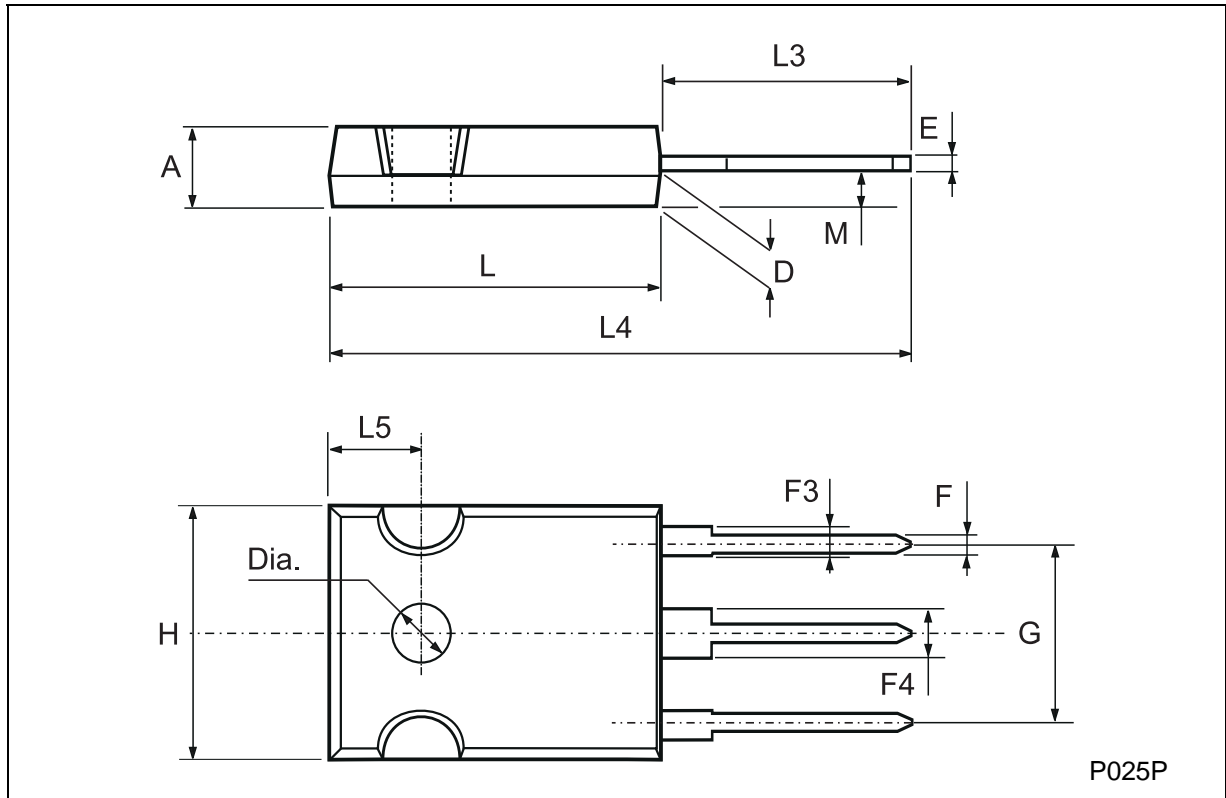
Total Switching Losses vs Collector Current





**TO-247 MECHANICAL DATA**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.7		5.3	0.185		0.209
D	2.2		2.6	0.087		0.102
E	0.4		0.8	0.016		0.031
F	1		1.4	0.039		0.055
F3	2		2.4	0.079		0.094
F4	3		3.4	0.118		0.134
G		10.9			0.429	
H	15.3		15.9	0.602		0.626
L	19.7		20.3	0.776		0.779
L3	14.2		14.8	0.559		0.582
L4		34.6			1.362	
L5		5.5			0.217	
M	2		3	0.079		0.118



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